

FIG. 2A

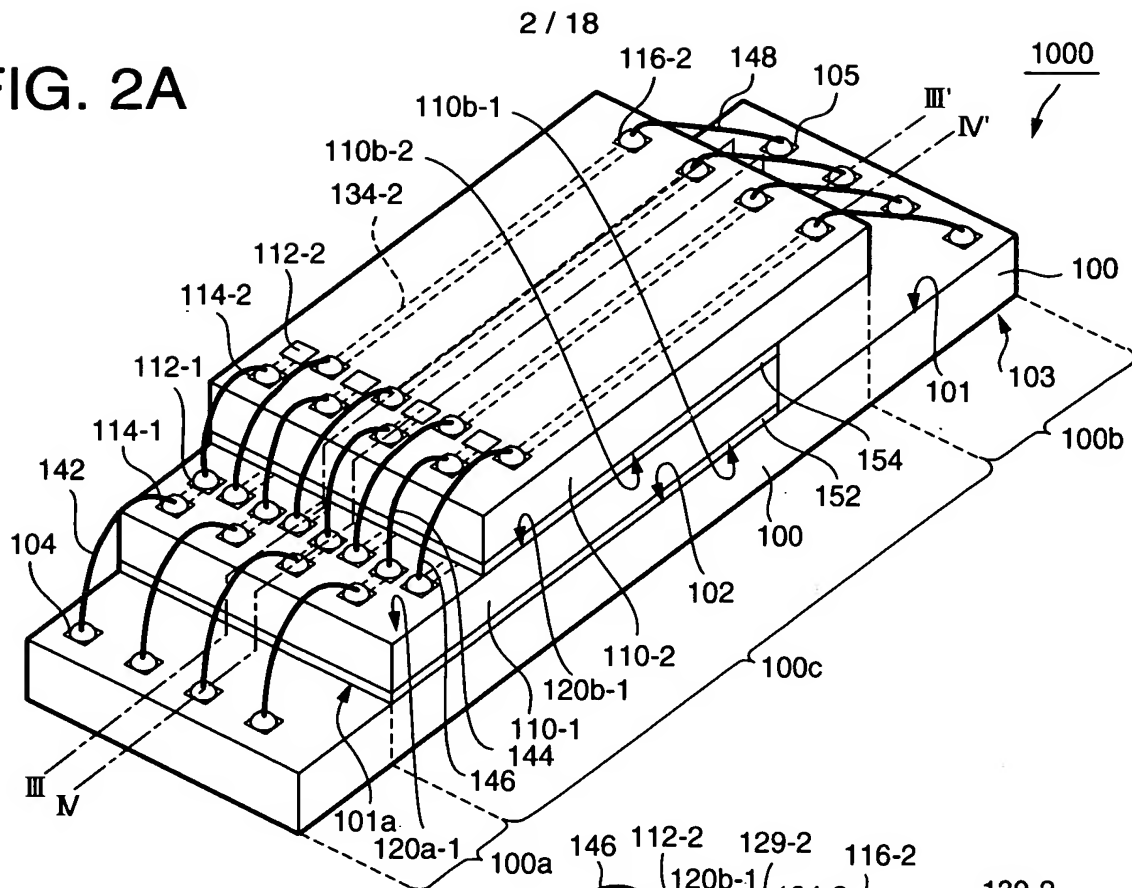


FIG. 2B

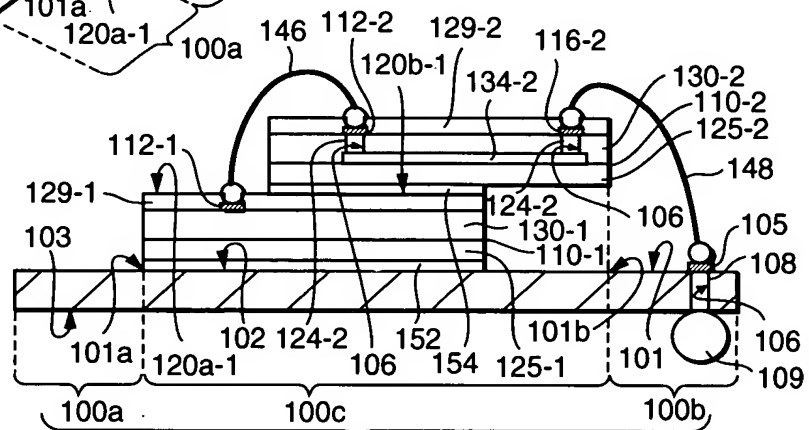
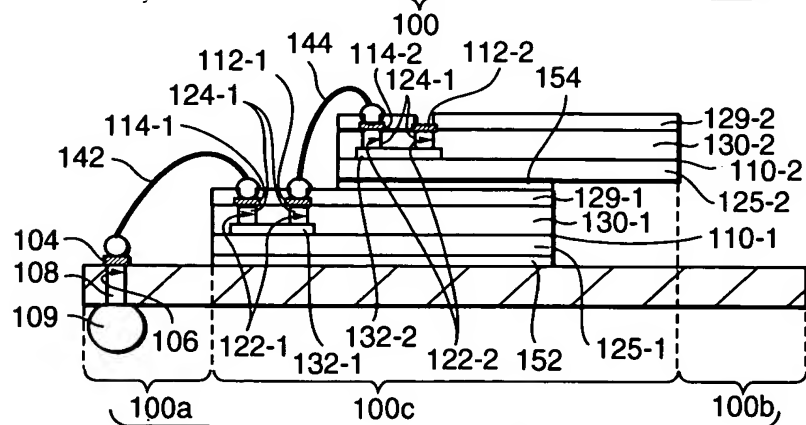


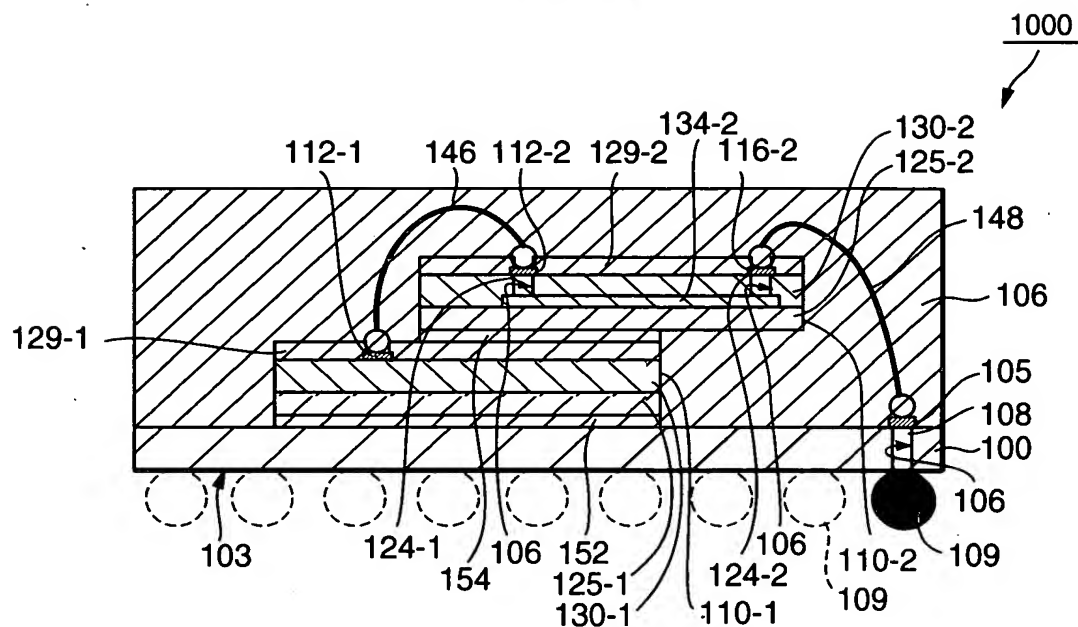
FIG. 2C



EXAMPLE OF LAMINATION OF SEMICONDUCTOR
CHIPS ACCORDING TO FIRST EMBODIMENT

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FIG. 3



EXAMPLE OF PACKAGING OF SEMICONDUCTOR CHIPS ACCORDING TO
FIRST EMBODIMENT

FIG. 4A

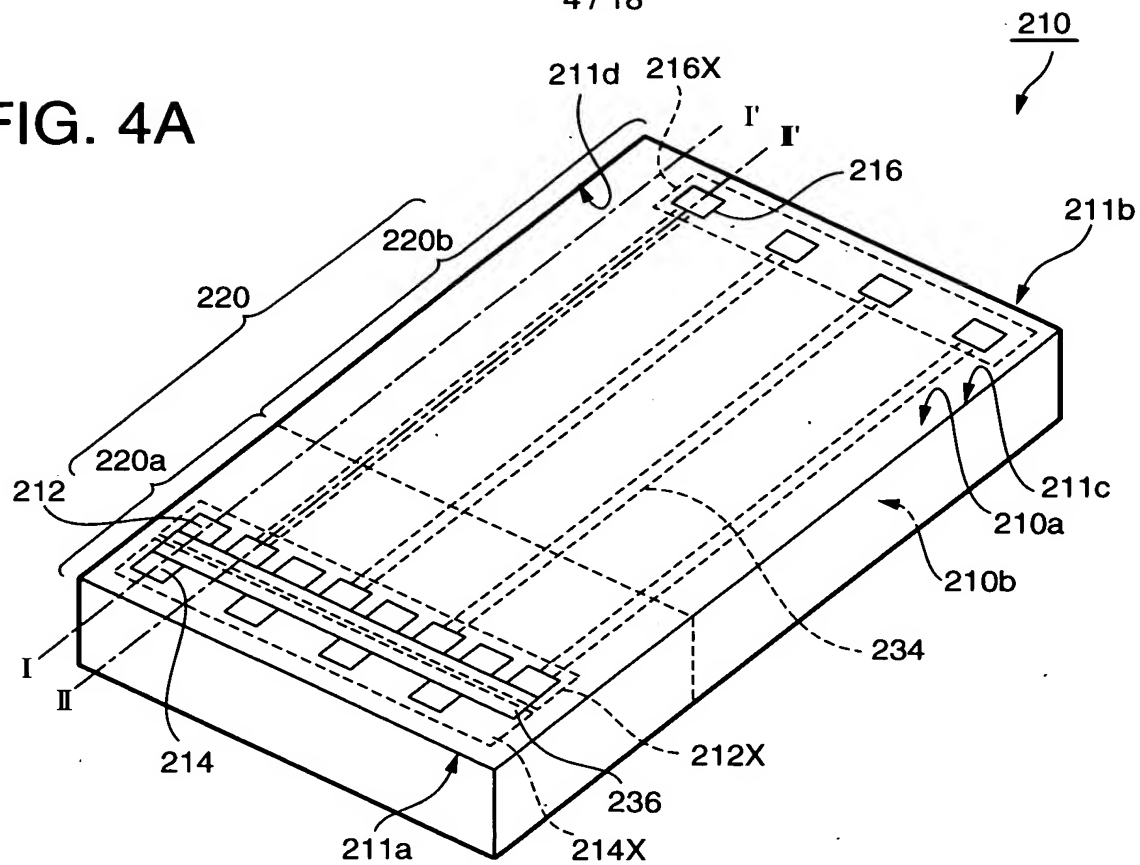


FIG. 4B

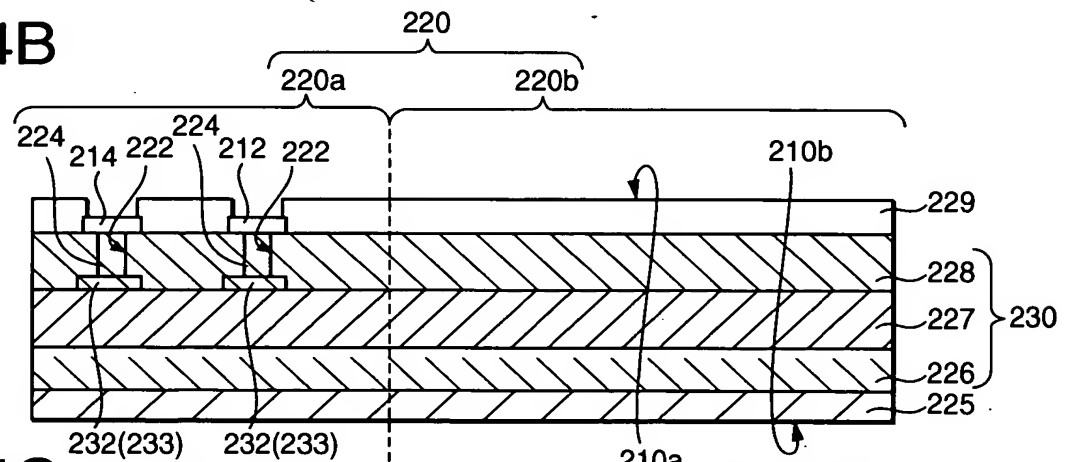
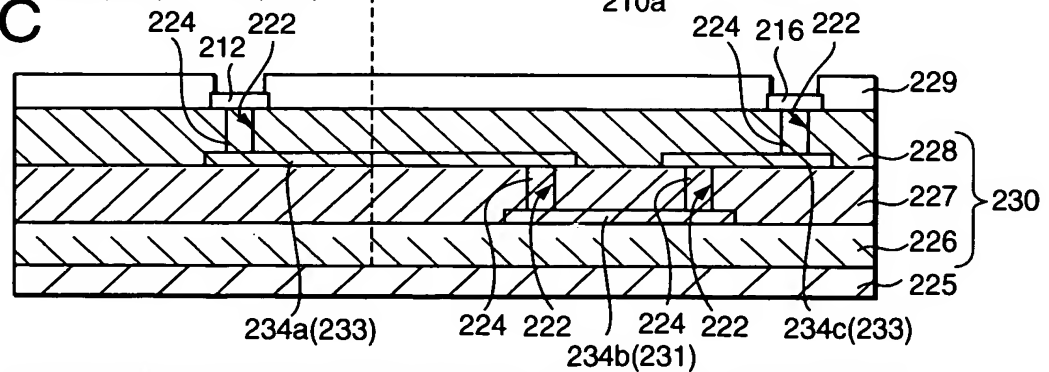


FIG. 4C



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SEMICONDUCTOR CHIP ACCORDING TO SECOND EMBODIMENT

FIG. 5A

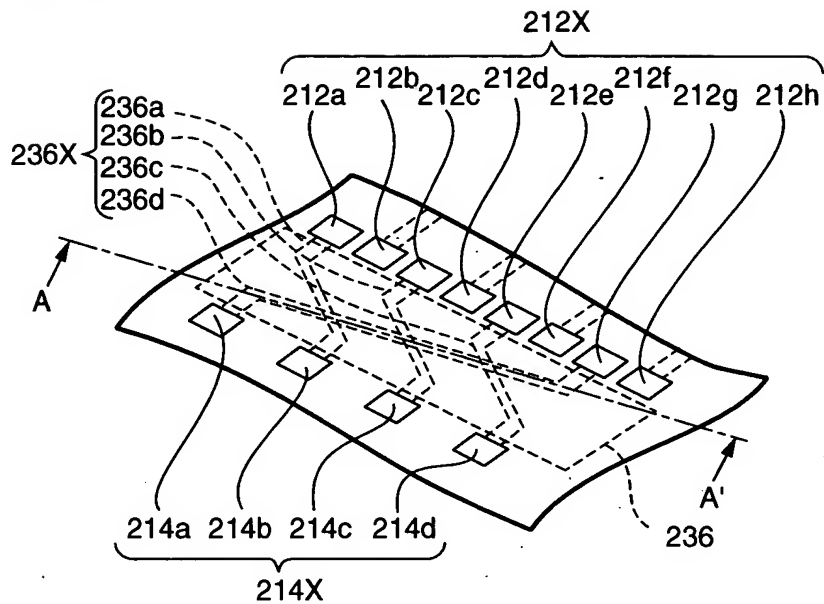
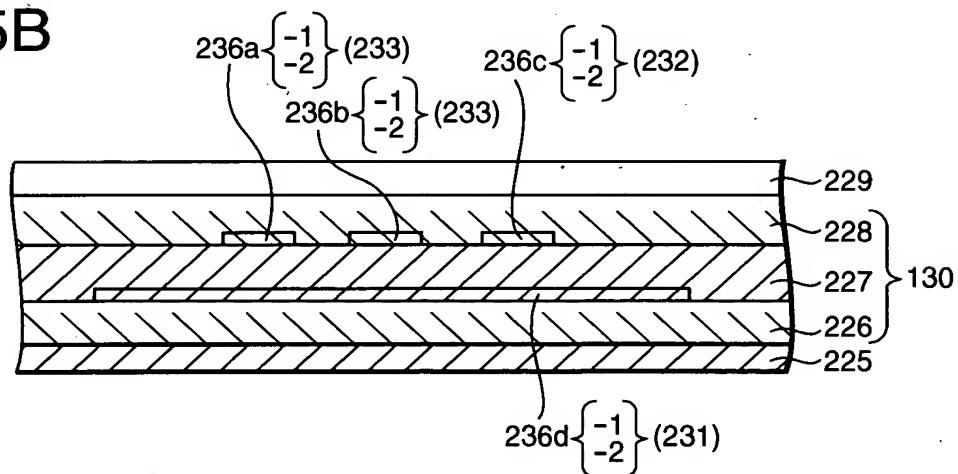


FIG. 5B



EXPLANATORY VIEW OF CONVERSION CIRCUIT ACCORDING TO
SECOND EMBODIMENT

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FIG. 6A

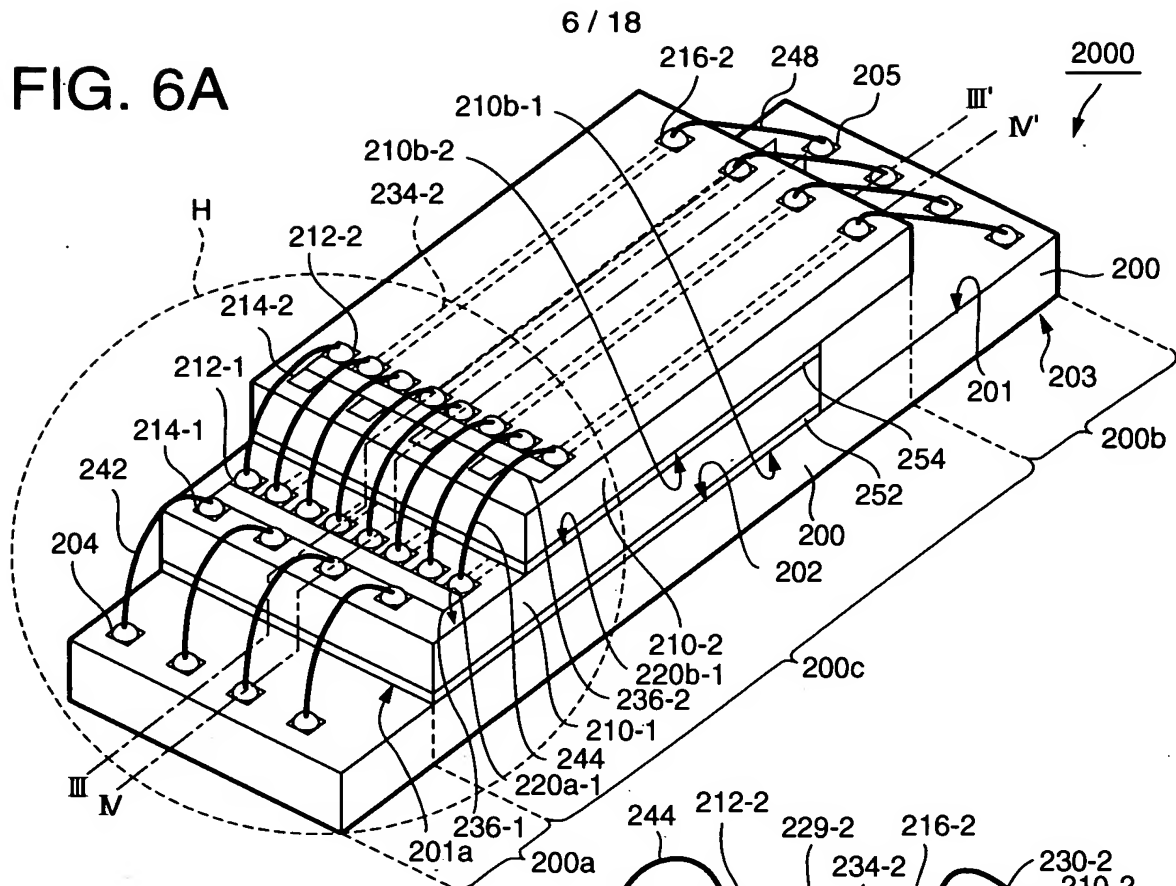


FIG. 6B

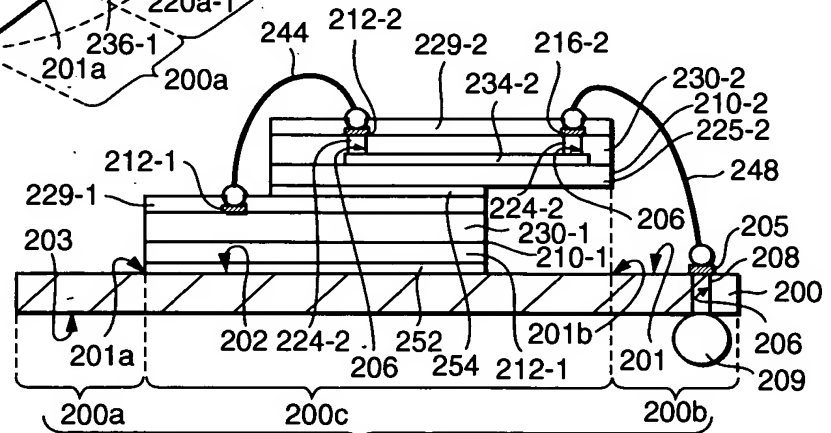
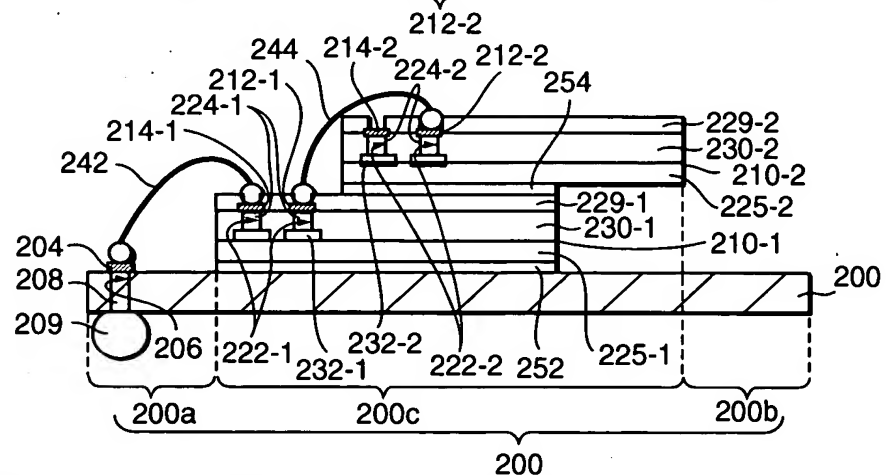


FIG. 6C



EXAMPLE OF LAMINATION OF SEMICONDUCTOR CHIPS ACCORDING TO SECOND EMBODIMENT

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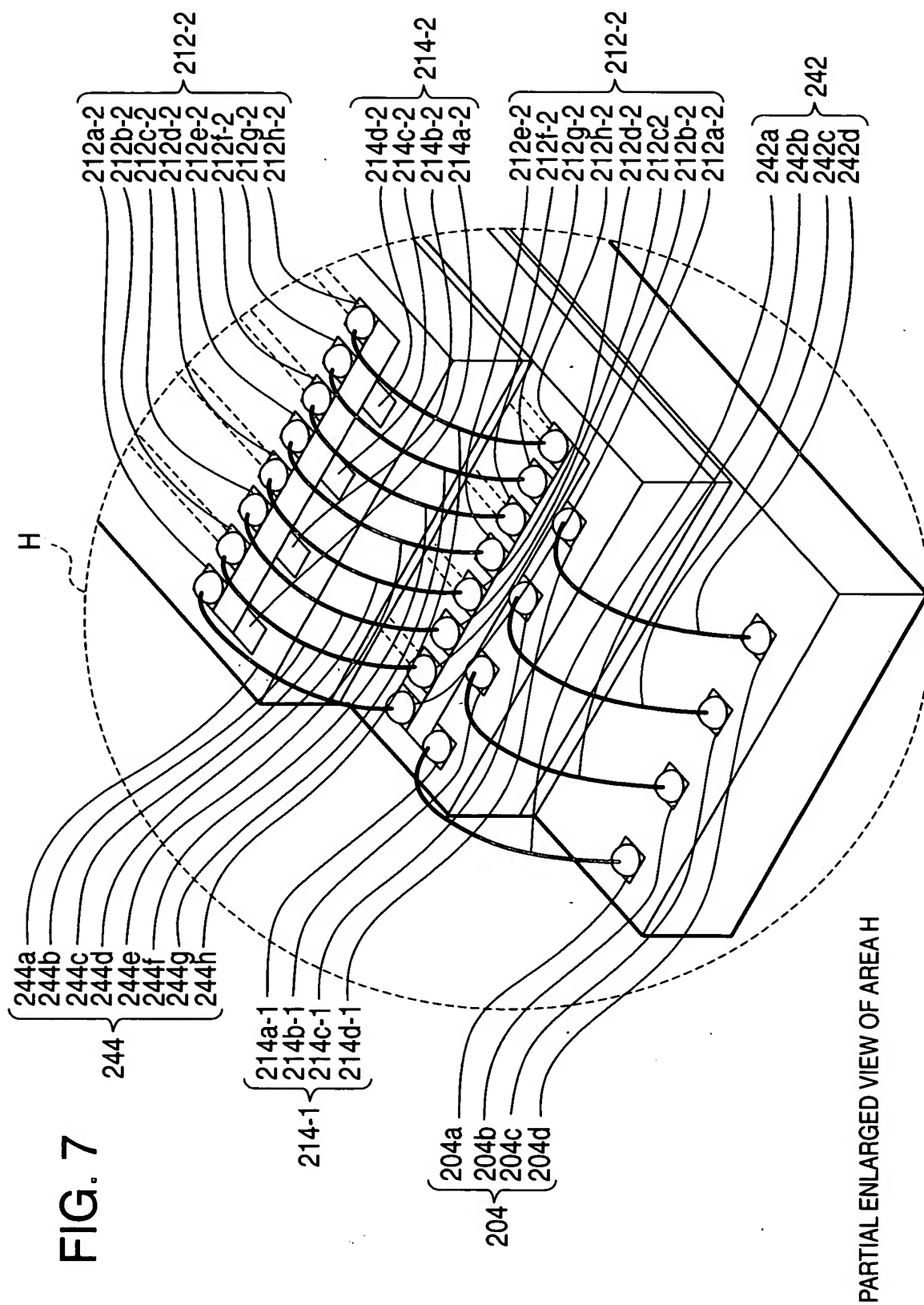
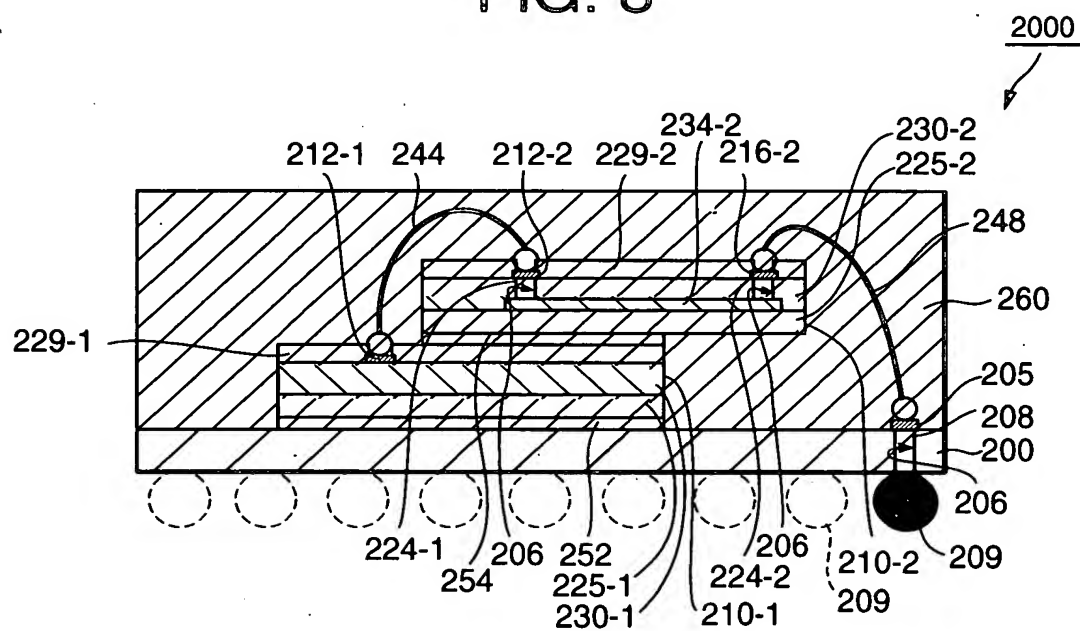


FIG. 8



EXAMPLE OF PACKAGING OF SEMICONDUCTOR CHIPS ACCORDING TO SECOND EMBODIMENT

FIG. 9A

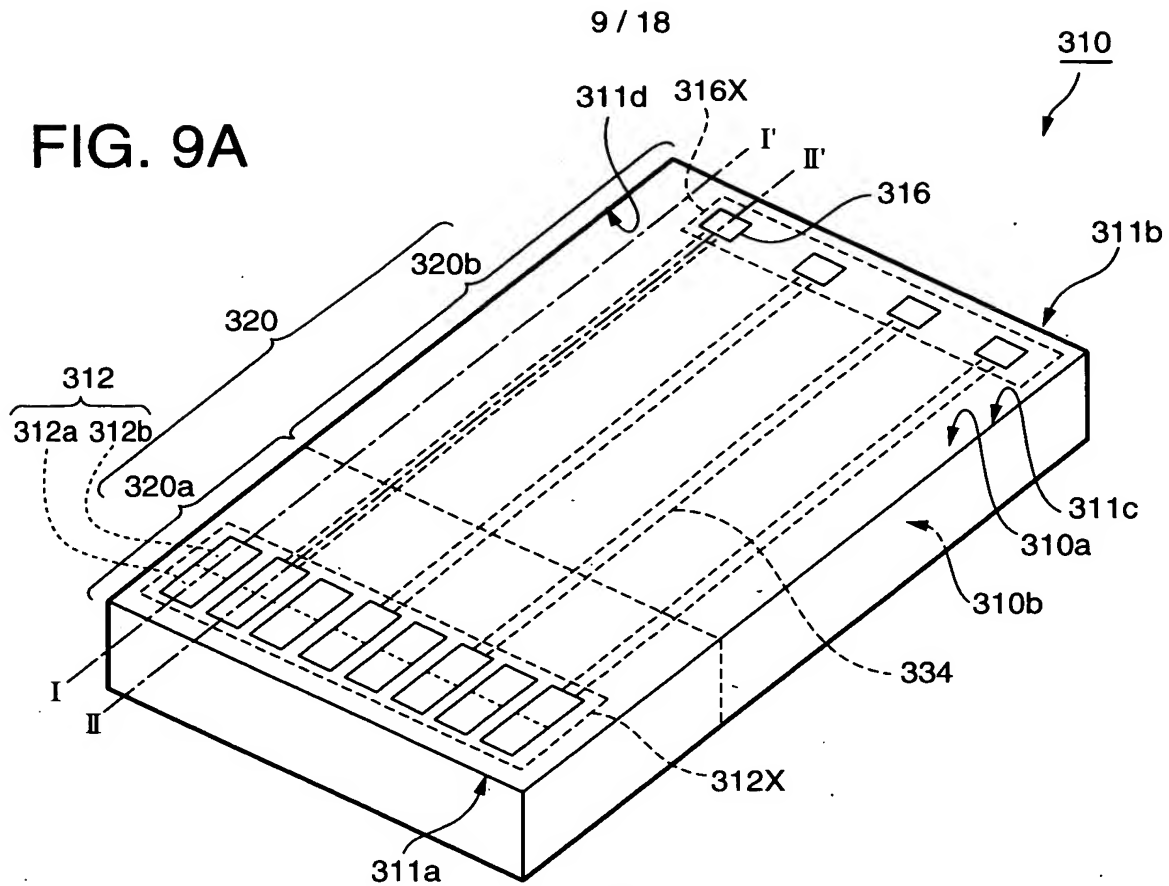


FIG. 9B

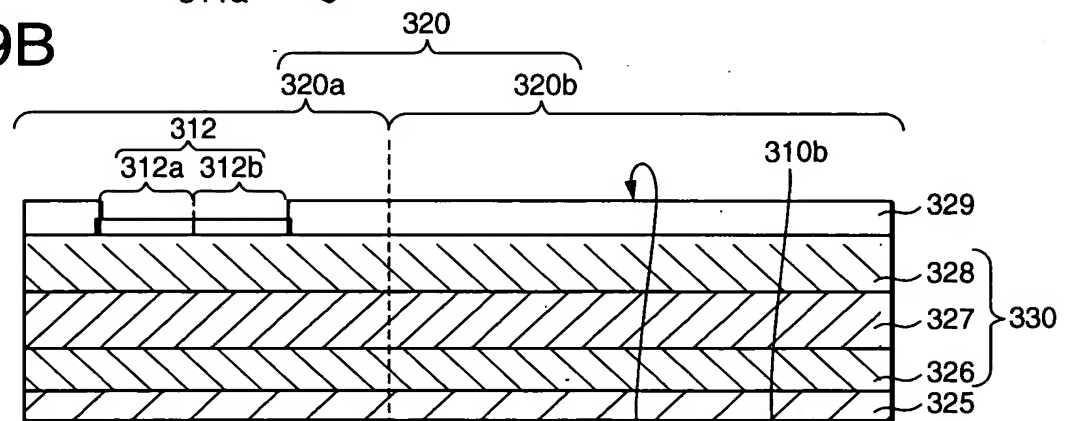
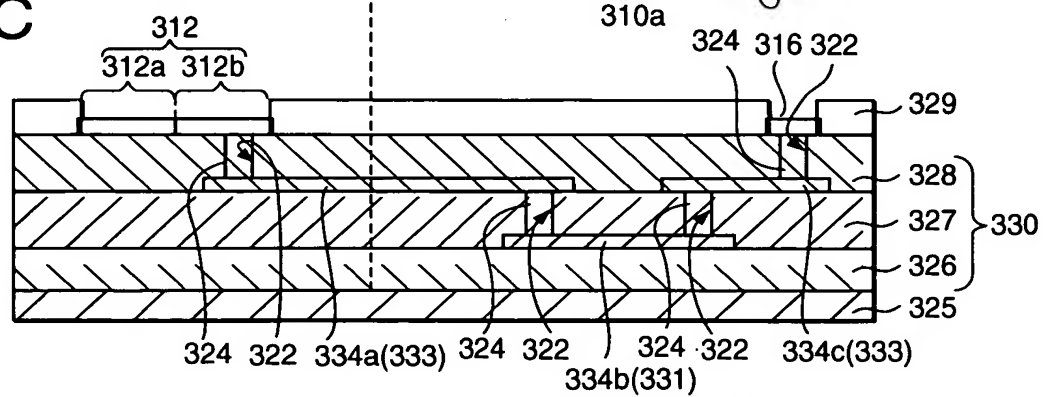


FIG. 9C



SEMICONDUCTOR CHIP ACCORDING TO THIRD EMBODIMENT

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FIG. 10A

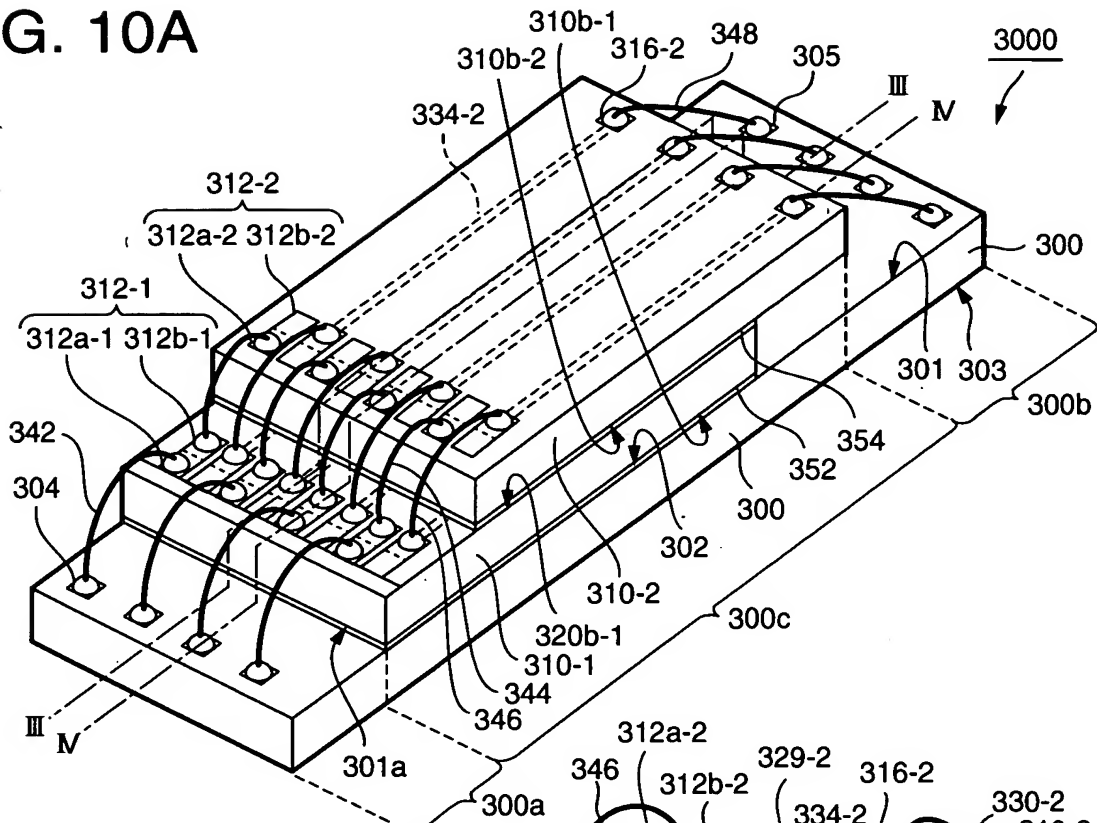


FIG. 10B

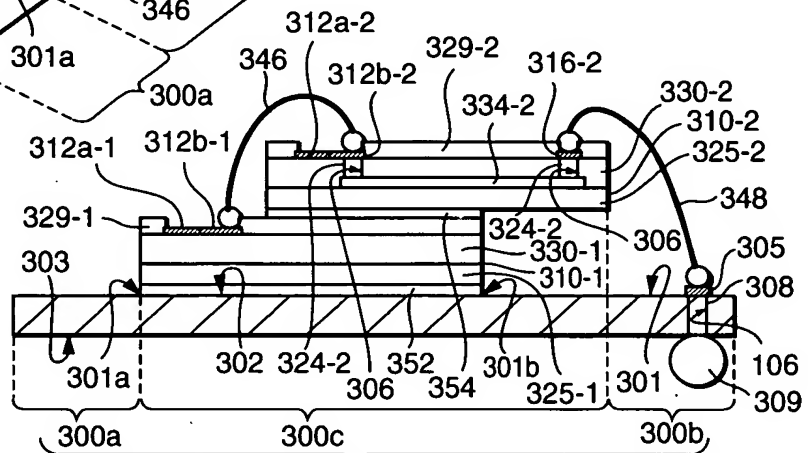
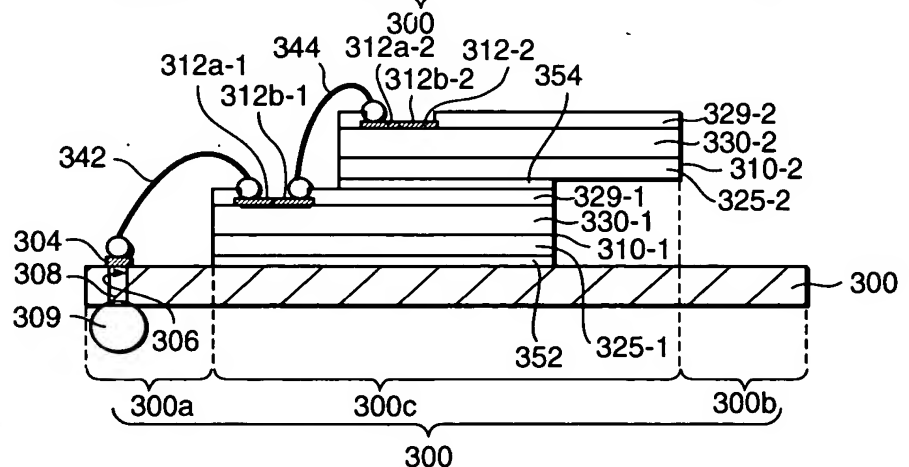
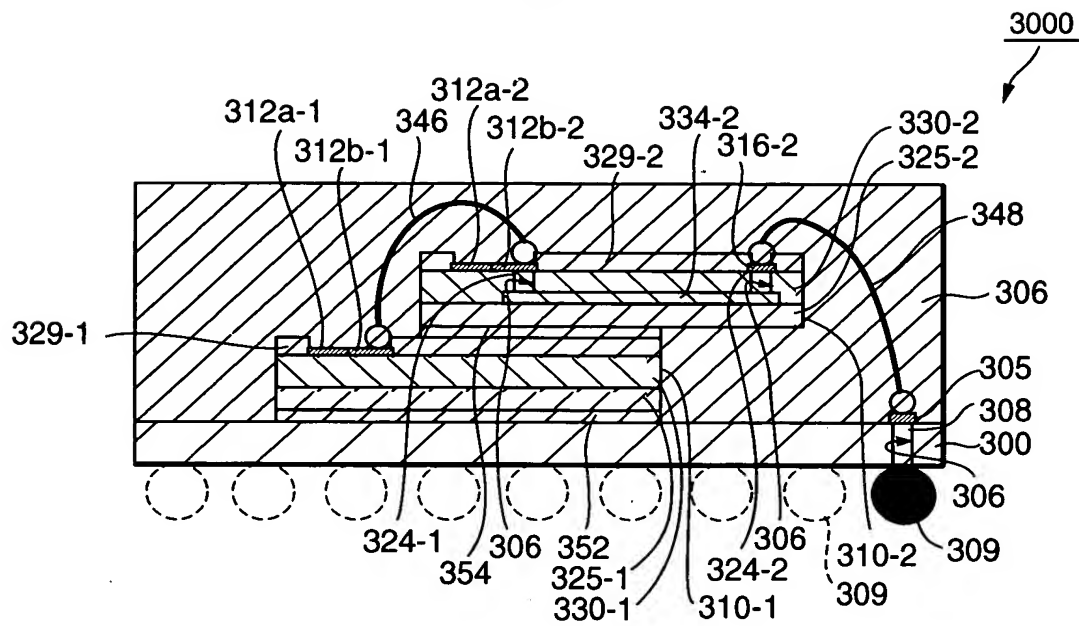


FIG. 10C



EXAMPLE OF LAMINATION OF SEMICONDUCTOR CHIPS ACCORDING TO
THIRD EMBODIMENT

FIG. 11



EXAMPLE OF PACKAGING OF SEMICONDUCTOR CHIPS ACCORDING TO
THIRD EMBODIMENT

FIG. 13A

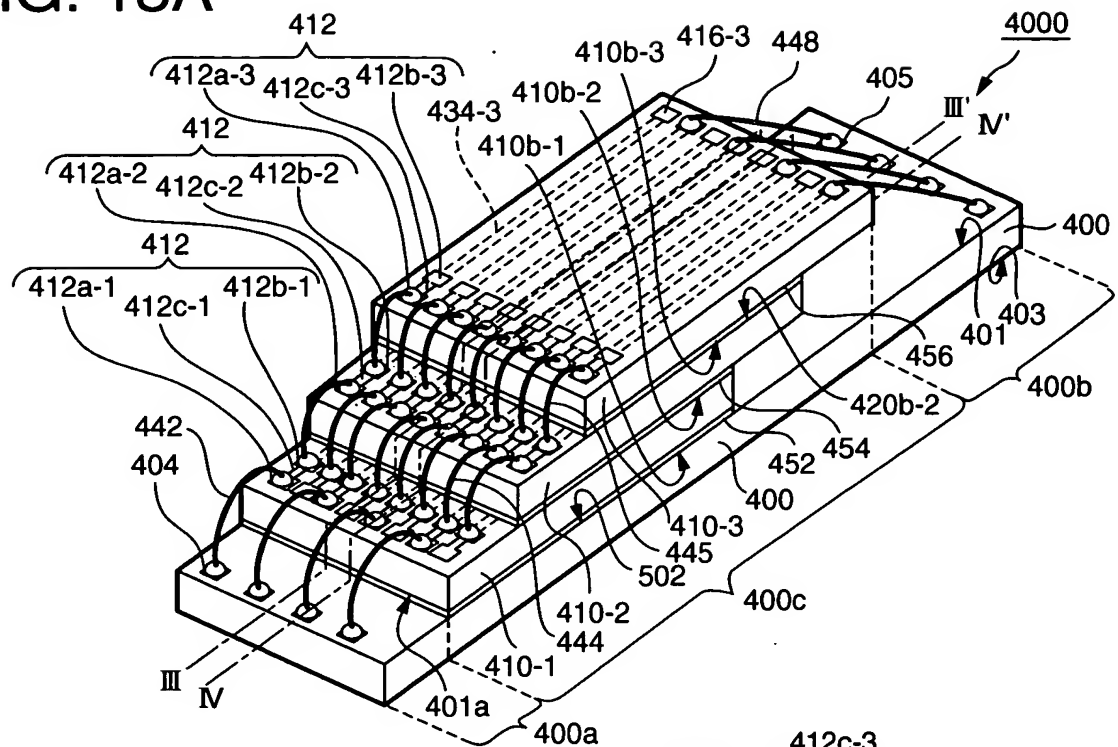


FIG. 13B

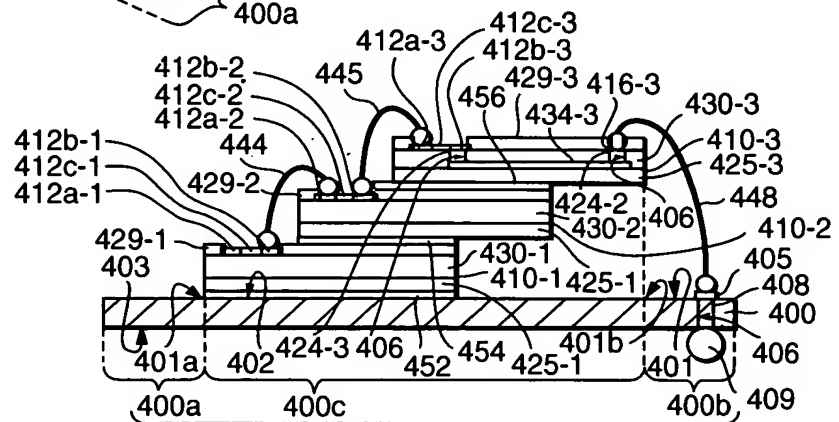
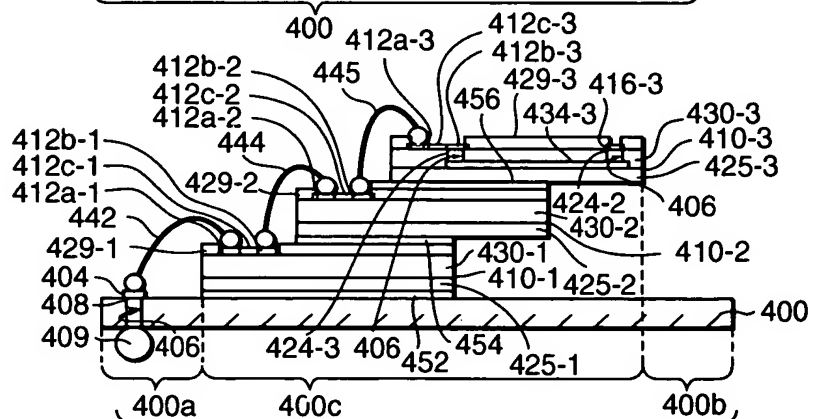
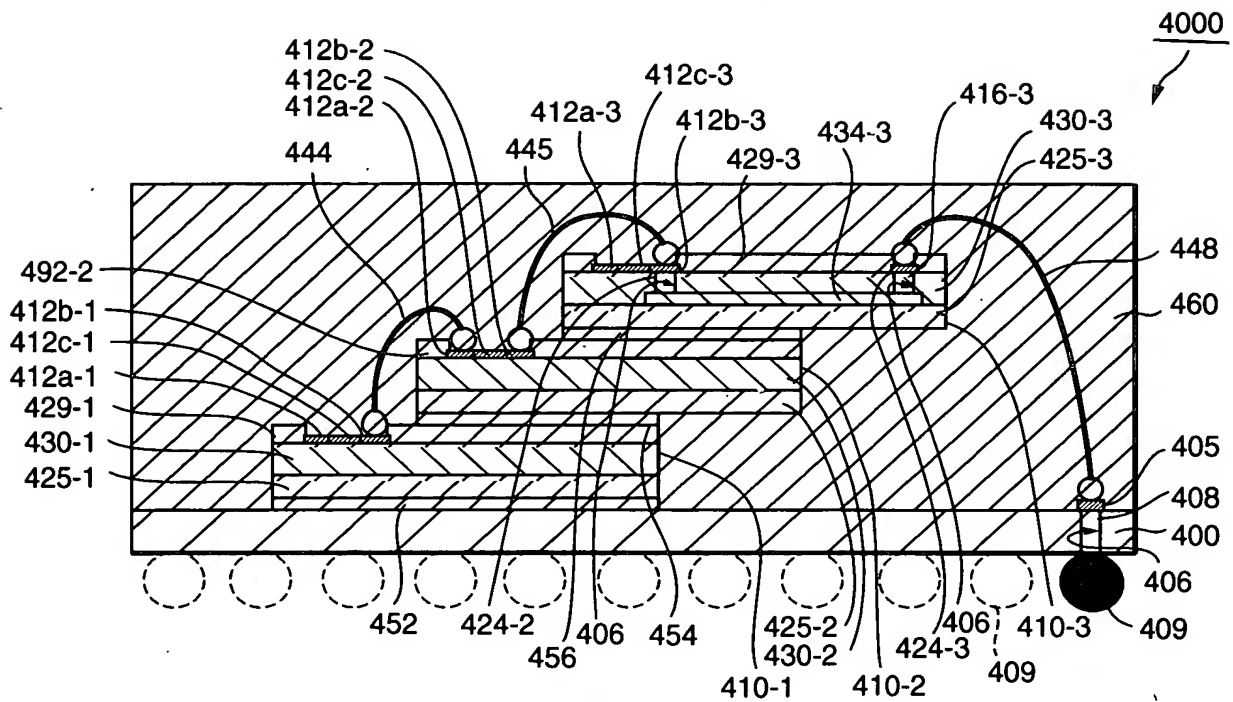


FIG. 13C



EXAMPLE OF LAMINATION OF SEMICONDUCTOR CHIPS
ACCORDING TO FOURTH EMBODIMENT

FIG. 14



EXAMPLE OF PACKAGING OF SEMICONDUCTOR CHIPS ACCORDING TO
FOURTH EMBODIMENT

FIG. 15A

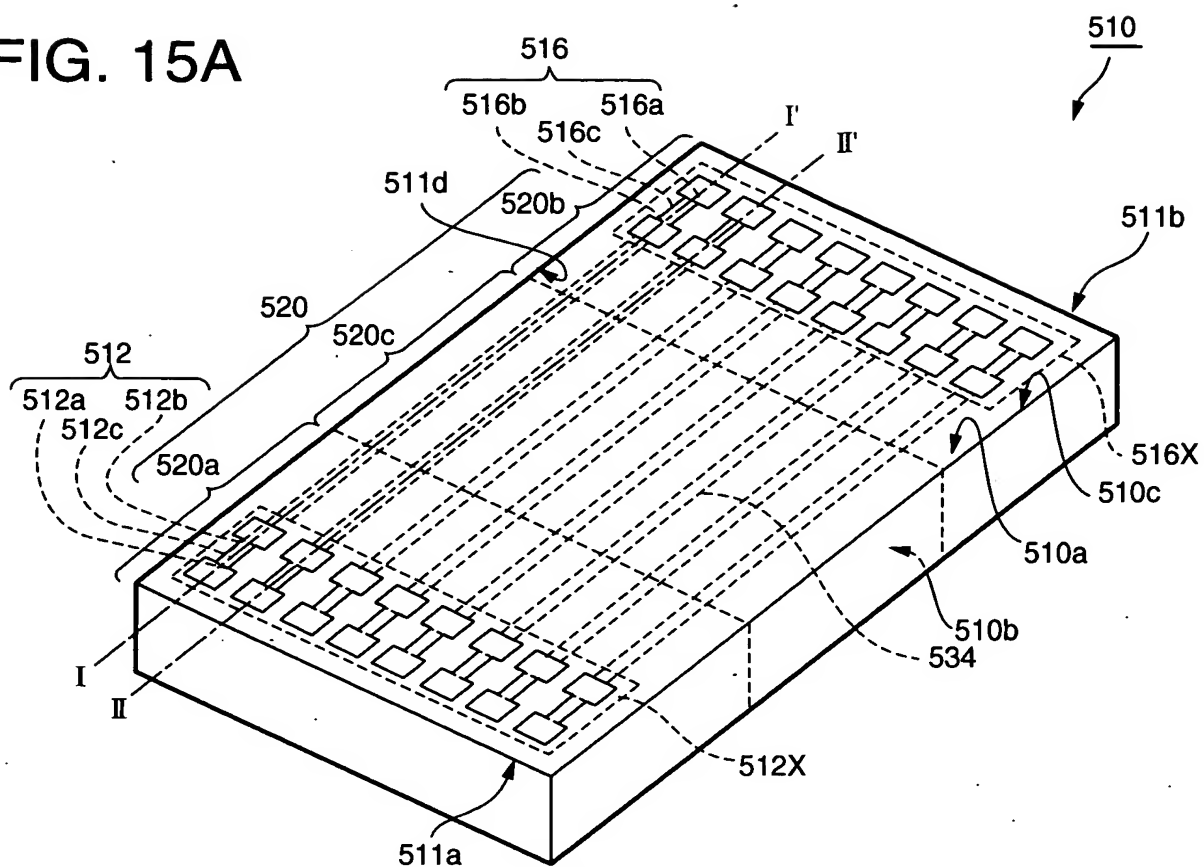
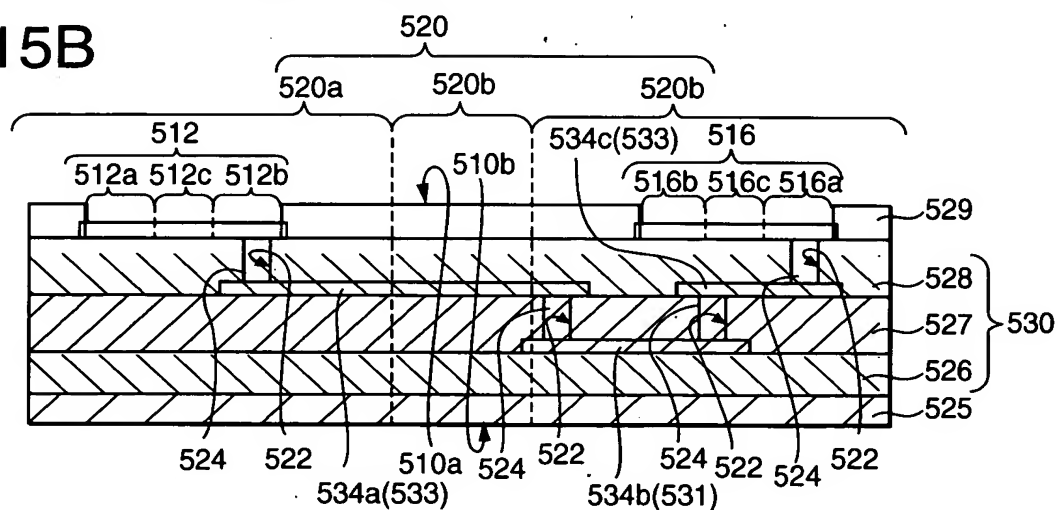
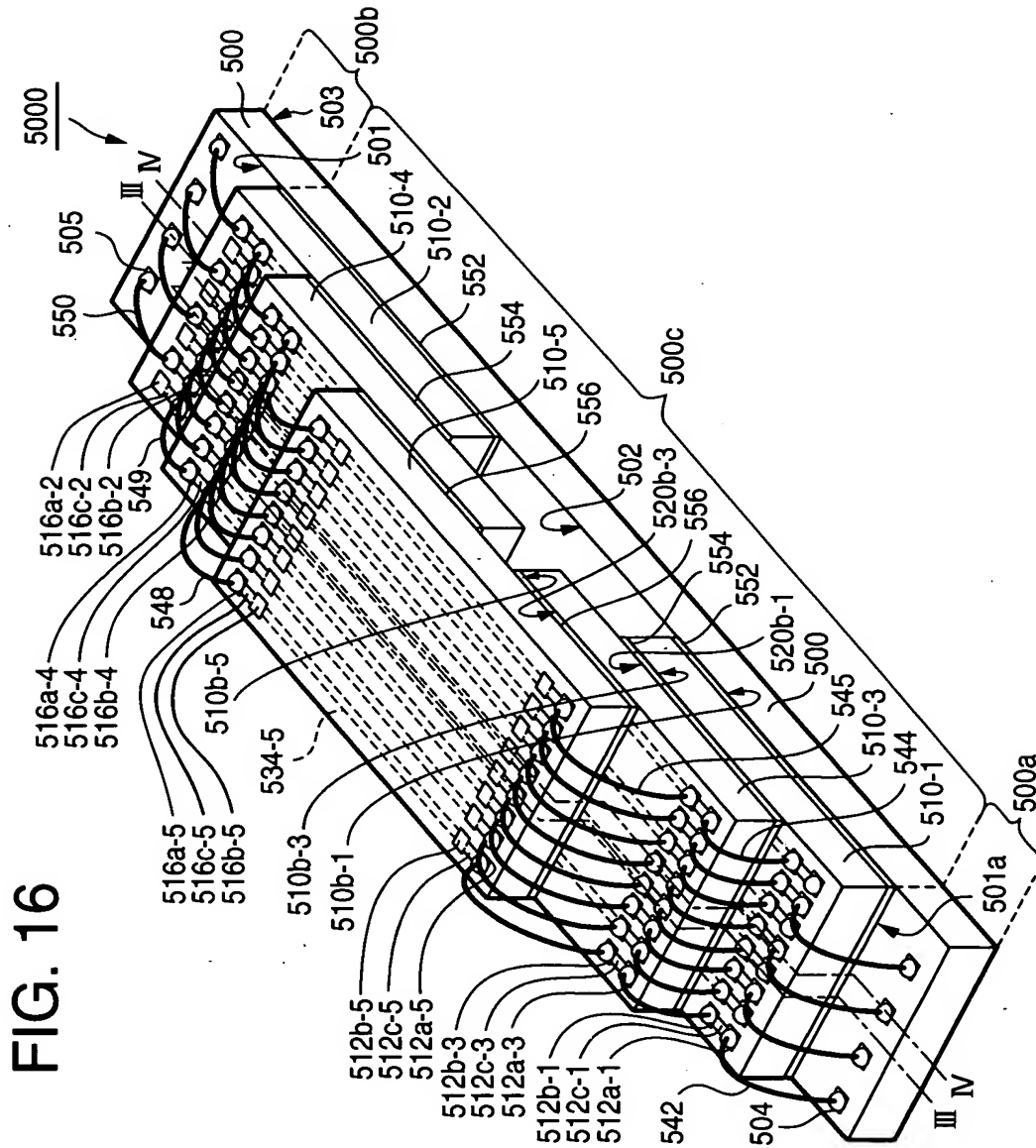


FIG. 15B



SEMICONDUCTOR CHIP ACCORDING TO FIFTH EMBODIMENT



EXAMPLE OF LAMINATION OF SEMICONDUCTOR CHIPS ACCORDING TO FIFTH EMBODIMENT

FIG. 17A

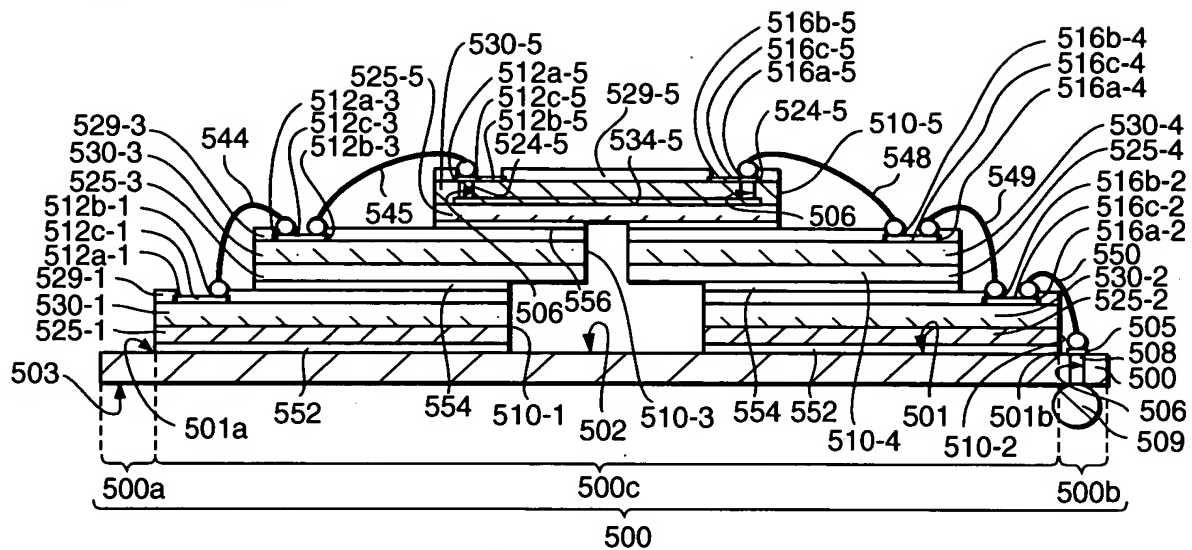
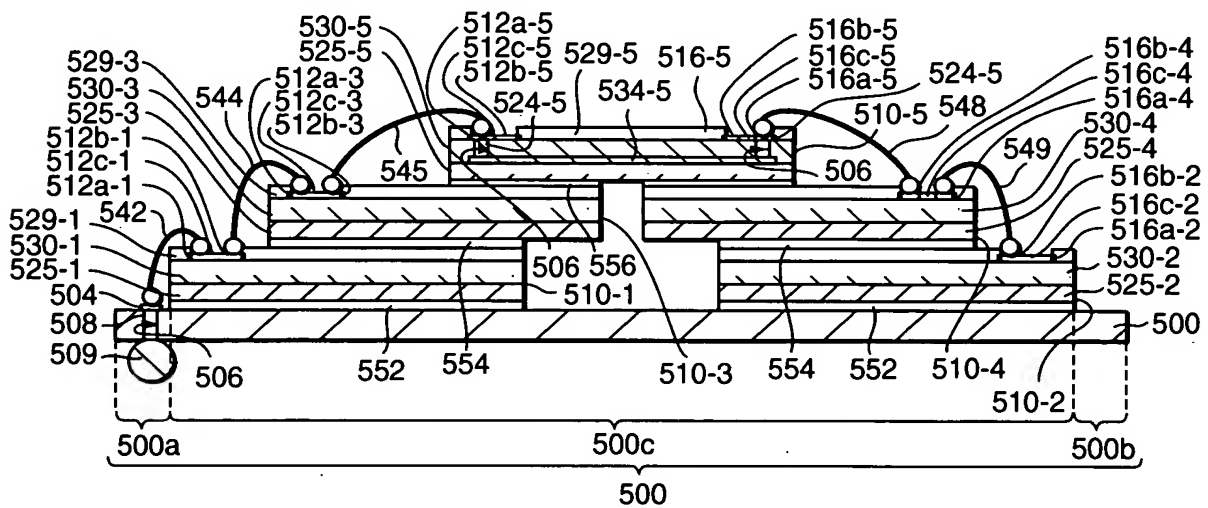
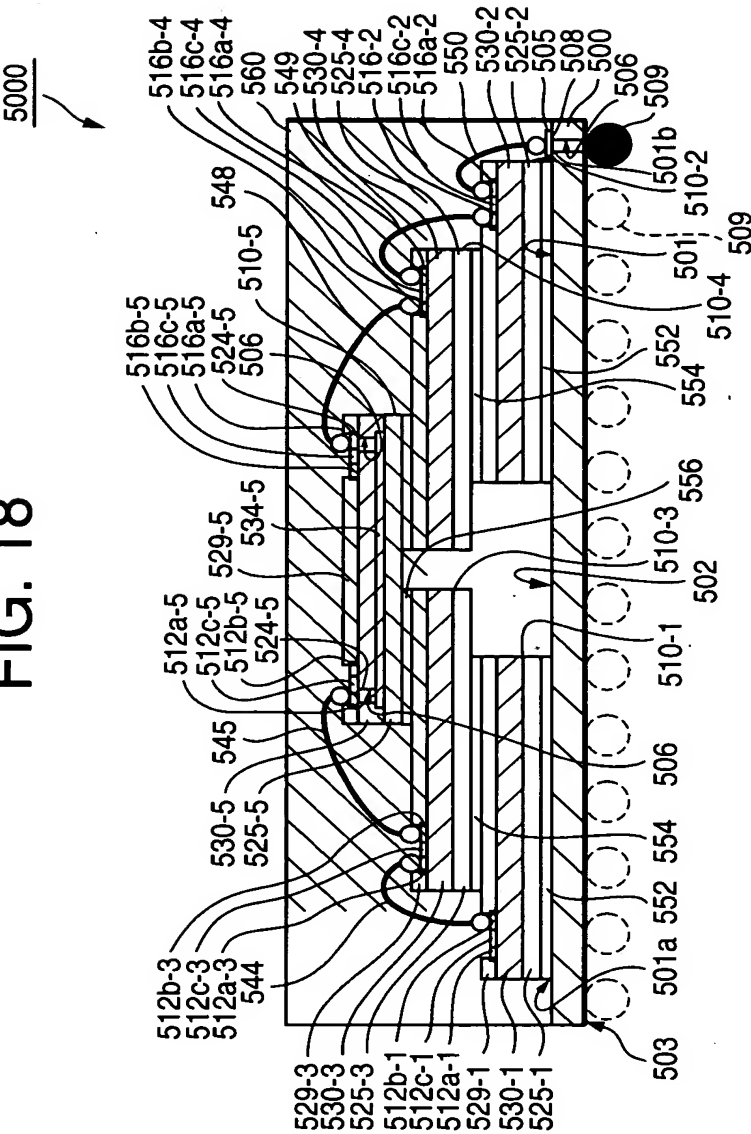


FIG. 17B



EXAMPLE OF LAMINATION OF SEMICONDUCTOR CHIPS ACCORDING TO FIFTH EMBODIMENT

FIG. 18



EXAMPLE OF PACKAGING OF SEMICONDUCTOR CHIPS ACCORDING TO FIFTH EMBODIMENT